

### 3 A LOW Vf Schottky Barrier Rectifier

#### DESCRIPTION

In Microsemi's new Powermite3<sup>®</sup> SMT package, these high efficiency ultrafast rectifiers offer the power handing capabilities previously found only in much larger packages. They are ideal for SMD applications that operate at high frequencies.

#### In addition to its size advantages, Powermite3<sup>®</sup> package features include a full metallic bottom that eliminates the possibility of solder flux entrapment during assembly, and a unique locking tab acts as an integral heat sink. Its innovative design makes this device ideal for use with

automatic insertion equipment.

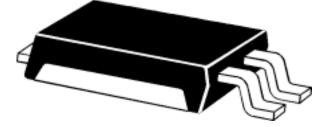
IMPORTANT: For the most current data, consult MICROSEMI's website: http://www.microsemi.com

ABSOLUTE MAXIMUM RATINGS AT 25° C (UNLESS OTHERWISE SPECIFIED)			
Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	40	v
RMS Reverse Voltage	V <sub>R (RMS)</sub>	28	V
Average Rectified Output Current	Ιo	3	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine wave Superimposed on Rated Load @ T <sub>c</sub> =100 °C	I <sub>FSM</sub>	50	А
Storage Temperature	T stg	-55 to +150	°C
Operating Temperature	Т ор	-55 to +125	°C

#### THERMAL CHARACTERISTICS (UNLESS OTHERWISE SPECIFIED)

Thermal Resistance			
Junction-to Bottom	Rja (1)	2.5	°C/Watt

(1) When Mounted on PC board with 2 ounce copper pattern.

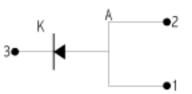


#### **KEY FEATURES**

- High power surface mount package.
- Guard Ring die construction for transient protection.
- Silicon Schottky rectifiers no reverse voltage recovery.
- Internal heat sink locking tabs
- Low forward voltage.
- Full metallic bottom eliminates flux entrapment
- Compatible with automatic insertion equipment
- Low profile-maximum height of 1mm supplied in 16 mm tape reel- 5000 units/ 13" reel.

#### APPLICATIONS/BENEFITS

- Switching and Regulating Power Supplies.
- Charge Pump Circuits.
- Reduces reverse recovery loss due to low I<sub>RM</sub>.
  - Small foot print 190 X 300 mils 1:1 Actual size



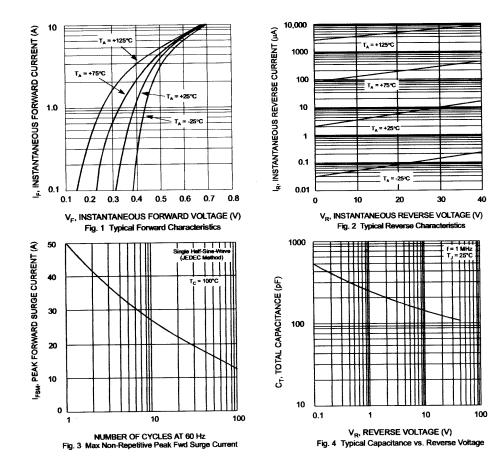
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ELECTRICAL PARAMETERS @ 25°C (unless otherwise specified)						
Parameter	Symbol	Conditions	Min	Тур.	Max	Units
Forward Voltage (Note 1)		I <sub>F</sub> = 3 A , T <sub>j</sub> =25 °C		0.46	0.50	
	V <sub>Fm</sub>	$I_F = 3 A$ , $T_j = 125 \ ^{\circ}C$ $I_F = 6 A$ , $T_j = 25 \ ^{\circ}C$		0.40 0.57	0.44 0.61	V
Reverse Break Down Voltage		I <sub>F</sub> = 6 A , T <sub>j</sub> =125 °C		0.54	0.58	
(Note 1)	V <sub>BR</sub>	I <sub>R</sub> = 0.5 mA	40			V
Reverse Current (Note1)	Im	V <sub>R</sub> = 40V, T <sub>j</sub> = 25 °C V <sub>R</sub> = 40V, T <sub>j</sub> =100 °C		15 10	500 20	uA mA
Capacitance	Ст	$V_{R} = 4 V; F = 1 MH_{Z}$		180		pF

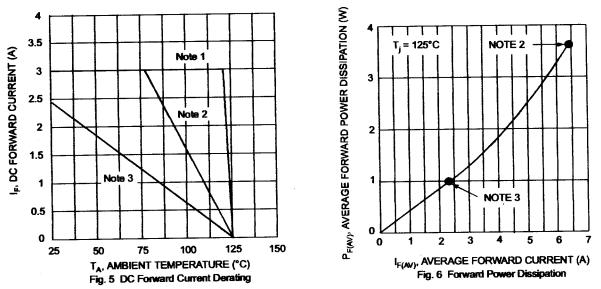
Note: 1 Short duration test pulse used to minimize self - heating effect.



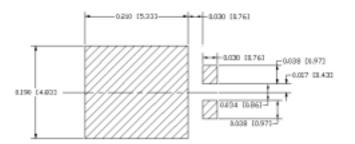
ELECTRICALS



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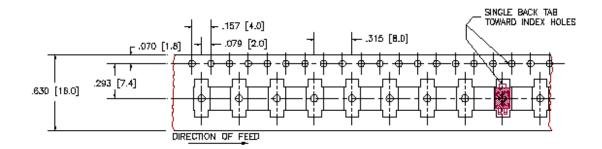
- Notes: 1. T<sub>A</sub> = T<sub>SOLDERING POINT</sub>, R<sub>ØJS</sub> = 3.4° C/W R<sub>Øsa</sub> = 0° C/W.
  2. Device mounted on GETEK substrate, 2" x 2", 2 oz. copper, double-sided, cathode pad dimensions .075" x 1.0", anode pad dimensions 0.25" x 1.0". R<sub>ØJA</sub> in range of 20-40° C/W.
  - 3. Device mounted on FRA-4 substrate, 2" x 2", 2 oz. copper, single-sided, pad layout  $R_{\Theta JA}$  in range of 95 115° C/W.



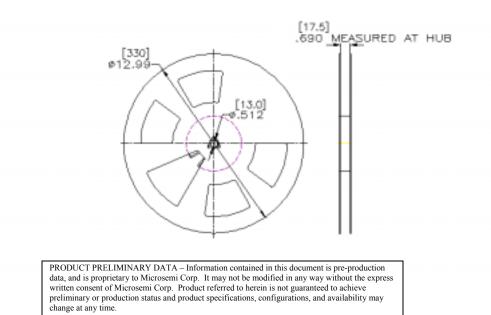


### 3 A LOW Vf Schottky Barrier Rectifier

16 mm TAPE



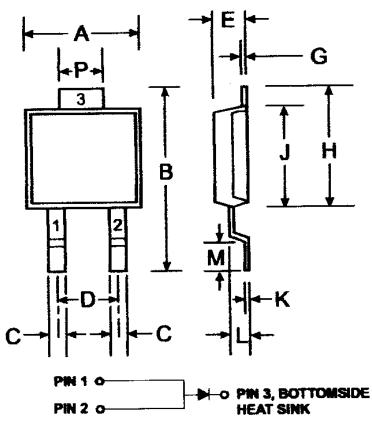
#### 13 INCH REEL



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A	4.03	4.09	
B	6.40	6.61	
С	.889 NOM		
D	1.83 NOM		
E	1.10	1.14	
G	.178 NOM		
Н	5.01	5.17	
J	4.37	4.43	
К	.178 NOM		
L	.71	.77	
M	.36	.46	
Р	1.73	1.83	
All Dimensions in mm			

POWERMITE®3

Min

Max

Dim

Note: Pins 1 & 2 must be electrically connected at the printed circuit board.

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▶	NOTES:

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